表面与界面工程

聚天冬氨酸对铜缓蚀作用的光电化学研究

朱律均,徐群杰,曹为民,万宗跃,印仁和,周国定,林昌健

上海电力学院环境工程系,国家电力公司热力设备腐蚀与防护部级重点实验室;上海大学理学院化 学系:厦门大学固体表面物理化学国家重点实验室

收稿日期 2007-4-28 修回日期 2007-10-10 网络版发布日期 2008-3-11 接受日期

摘要

用光电化学方法研究了绿色水处理药剂聚天冬氨酸对铜的缓蚀作用,铜在硼酸-硼砂缓冲溶液(pH=9.2)中,表面▶加入引用管理器 的Cu₂0膜显p-型光响应,添加适量缓蚀剂聚天冬氨酸(PASP)后,PASP吸附在铜电极表面成膜促使Cu₂0膜增厚, 体现在电位在负向扫描过程中Cu₂0膜的p-型光电流增大。 p-型光电流越大,缓蚀性能越好。当PASP浓度为3 mg· L^{-1} 时, Cu_{2} 0膜的p-型光电流最大,缓蚀性能最好。 $C1^{-}$ 的存在会阻止PASP在铜电极表面的吸附,使 Cu_{2} 0膜暴露而 受侵蚀,导致了PASP的缓蚀性能变差。

关键词 聚天冬氨酸 光电化学 缓蚀剂 铜 分类号

Photoelectrochemical study of inhibition mechanism of PASP on copper

ZHU Lüjun, XU Qunjie, CAO Weimin, WAN Zongyue, YIN Renhe, ZHOU Guoding, LIN Changjian

Department of Environment Engineering Shanghai University of Electric Power; Department of Chemistry, College of Science, Shanghai University; State Key Laboratory of Solid Surface Physical Chemistry, Xiamen University

Abstract

The inhibition mechanism of polyaspartic (PASP) on copper electrode in a borax buffer solution was studied by the photocurrent response method. The copper electrode in a borax buffer solution showed p-type photocurrent response which came from Cu₂O layer on its surface. The photocurrent response during cathodic polarization became bigger when inhibitor PASP which could be adsorbed on the Cu electrode and make Cu₂O layer thicker was added. The bigger the photocurrent response, the better the inhibition effect. When adding PASP with a concentration of 3 mg·L⁻¹, the photocurrent response was the biggest and inhibition of copper corrosion was the best. Cl⁻ could prevent PASP from being absorbed and make Cu₂O layer unprotected, resulting in worse inhibition.

Key words

PASP photoelectrochemistry inhibitor copper

DOI:

扩展功能

本文信息

- ▶ Supporting info
- ▶ PDF(522KB)
- ▶[HTML全文](0KB)
- ▶参考文献

服务与反馈

- ▶把本文推荐给朋友
- ▶加入我的书架
- ▶复制索引
- Email Alert
- 文章反馈
- ▶浏览反馈信息

相关信息

▶ 本刊中 包含"聚天冬氨酸"的 相关文章

▶本文作者相关文章

- 朱律均
- 徐群杰
- 曹为民
- 万宗跃
- 印仁和
- 周国定
- 林昌健